

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (Original) An image sensor package comprising:
an image sensor die comprising an approximately or completely planar photosensing surface which receives external light and converts the received light into an electrical signal, a plurality of bond pads at the peripheral side of the photosensing surface, and an approximately or completely planar non-photosensing surface on the side opposite to the photosensing surface and the bond pads;

a substrate comprising an insulating layer comprising an approximately or completely planar first surface to which the non-photosensing surface of the image sensor die is adhered by an adhesive and an approximately or completely planar second surface on the opposite side thereof, a plurality of electrically conductive patterns being formed on each of the first and second surfaces;

a plurality of conductive wires electrically connecting the bond pads of the image sensor die to the electrically conductive patterns on the first surface of the insulating layer;

a support wall on the first surface of the insulating layer of the substrate around the periphery of the conductive wires and comprising a plurality of screw threads on the outer peripheral surface thereof; and

a mount comprising an aperture into which a barrel comprising a plurality of lenses is mounted.

2. (Original) The image sensor package as claimed in claim 1, wherein at least one passive element is further

provided on the substrate at the outer peripheral side of the support wall.

3. (Original) The image sensor package as claimed in claim 1, wherein the barrel further includes an infrared blocking glass disposed below the plurality of lenses.

4. (Original) The image sensor package as claimed in claim 1, wherein a flexible circuit is connected to the electrically conductive patterns formed on the second surface of the insulating layer of the substrate.

5. (Original) An image sensor package comprising:
a semiconductor die comprising an approximately or completely planar first surface and an approximately or completely planar second surface on the opposite side thereof, a plurality of bond pads to which conductive bumps are bonded being formed on the second surface;

a substrate comprising an insulating layer comprising an approximately or completely planar first surface and an approximately or completely planar second surface on the opposite side thereof, a plurality of electrically conductive patterns being formed on each of the first and second surfaces, the conductive bumps of the semiconductor die being electrically connected to the electrically conductive patterns of the first surface of the insulating layer;

a mount on the first surface of the insulating layer of the substrate at the peripheral side of the semiconductor die and comprising a support plate which extends inward and which has an aperture at the center thereof;

an image sensor die comprising an approximately or completely planar photosensing surface which receives external light and converts the light into an electrical signal, a plurality of bond pads formed at the peripheral side of the

photosensing surface and an approximately or completely planar non-photosensing surface on the side opposite to the photosensing surface and the bond pads, a plurality of conductive bumps connected to the support plate being formed on the bond pads; and

a barrel comprising a plurality of lenses and engaged into the mount above the support plate by a screw connection.

6. (Original) The image sensor package as claimed in claim 5, wherein the aperture of the support plate is formed in a position corresponding to the photosensing surface of the image sensor die.

7. (Original) The image sensor package as claimed in claim 5, wherein an underfill is filled between the semiconductor die and the substrate in order to improve the mechanical bond strength between the semiconductor die and the substrate.

8. (Original) The image sensor package as claimed in claim 5, wherein an underfill is filled between the image sensor die and the support plate in order to improve the mechanical bond strength between the image sensor die and the support plate.

9. (Original) The image sensor package as claimed in claim 5, wherein an electrically conductive pattern is formed on the lower surface of the support plate and the inner wall of the mount below the support plate and electrically connected to the electrically conductive bumps of the image sensor die.

10. (Original) The image sensor package as claimed in claim 5, wherein the barrel further includes an infrared blocking glass.

11. (Original) The image sensor package as claimed in claim 5, wherein at least one passive element is further provided on the substrate at the outer or inner peripheral side of the mount.

12. (Original) The image sensor package as claimed in claim 5, wherein a flexible circuit is connected to the electrically conductive patterns formed on the second surface of the insulating layer of the substrate.

13-20. (Canceled)

21. (New) The image sensor package as claimed in claim 5, wherein a plurality of screw threads are formed on the inner peripheral surface of the mount above the support plate.

22. (New) The image sensor package as claimed in claim 21, wherein a plurality of screw threads are formed on the outer peripheral surface of the barrel.

23. (New) The image sensor package as claimed in claim 22 wherein the screw threads of the mount are engaged with the screw threads of the barrel.

24. (New) The image sensor package as claimed in claim 23 wherein a distance between the barrel and the image sensor die is adjusted by turning the barrel.

25. (New) The image sensor package as claimed in claim 1 wherein the mount comprises a plurality of screw threads on the outer peripheral surface of the mount.

26. (New) The image sensor package as claimed in claim 25 wherein the screw threads of the mount are engaged with the screw threads of the support wall.

27. (New) The image sensor package as claimed in claim 26 wherein a distance between the barrel and the image sensor die is adjusted by turning the mount.

28. (New) An image sensor package comprising:
a semiconductor die comprising an approximately or completely planar first surface and an approximately or completely planar second surface on the opposite side thereof, a plurality of bond pads to which conductive bumps are bonded being formed on the second surface;

a substrate comprising an insulating layer comprising an approximately or completely planar first surface and an approximately or completely planar second surface on the opposite side thereof, a plurality of electrically conductive patterns being formed on each of the first and second surfaces, the conductive bumps of the semiconductor die being electrically connected to the electrically conductive patterns of the first surface of the insulating layer;

a mount on the first surface of the insulating layer of the substrate at the peripheral side of the semiconductor die and comprising:

a support plate which extends inward and which has an aperture at the center thereof; and

a plurality of screw threads on the inner peripheral surface of the mount above the support plate;

an image sensor die comprising an approximately or completely planar photosensing surface which receives external light and converts the light into an electrical signal, a plurality of bond pads formed at the peripheral side of the photosensing surface and an approximately or completely planar

non-photosensing surface on the side opposite to the photosensing surface and the bond pads, a plurality of conductive bumps connected to the support plate being formed on the bond pads; and

a barrel comprising:

a plurality of lenses; and

a plurality of screw threads on the outer peripheral surface of the barrel, wherein the screw threads of the mount are engaged with the screw threads of the barrel.